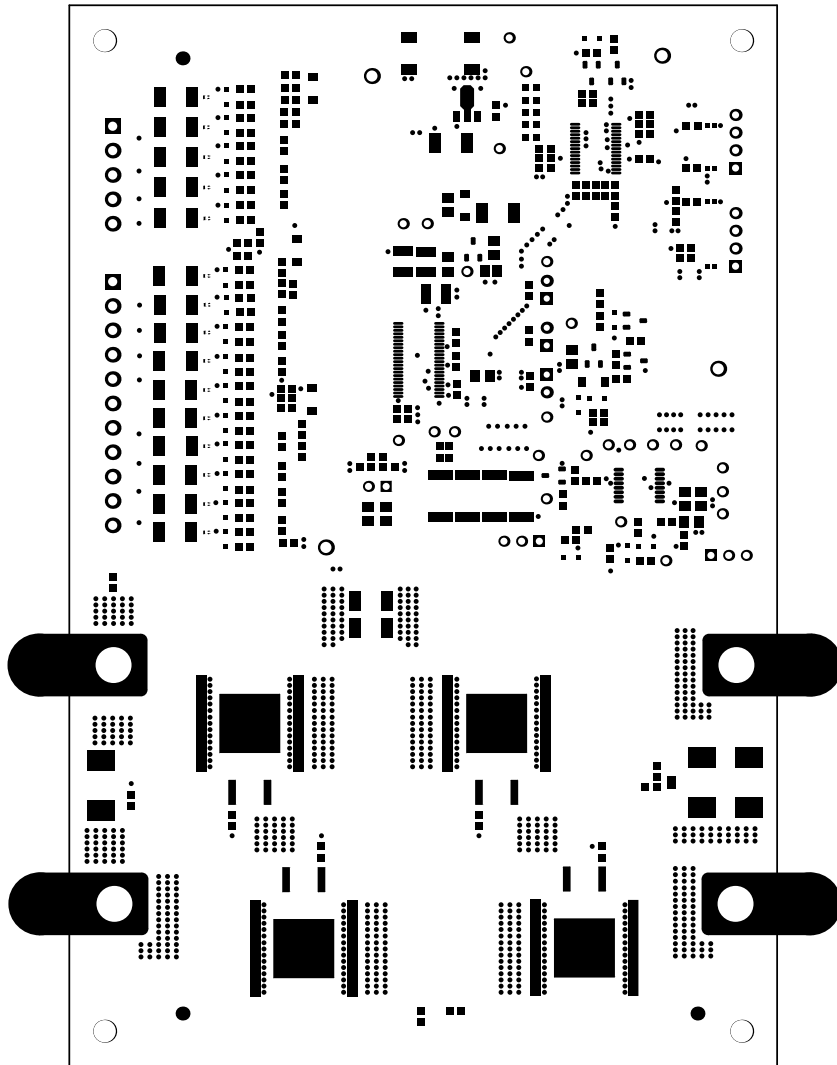
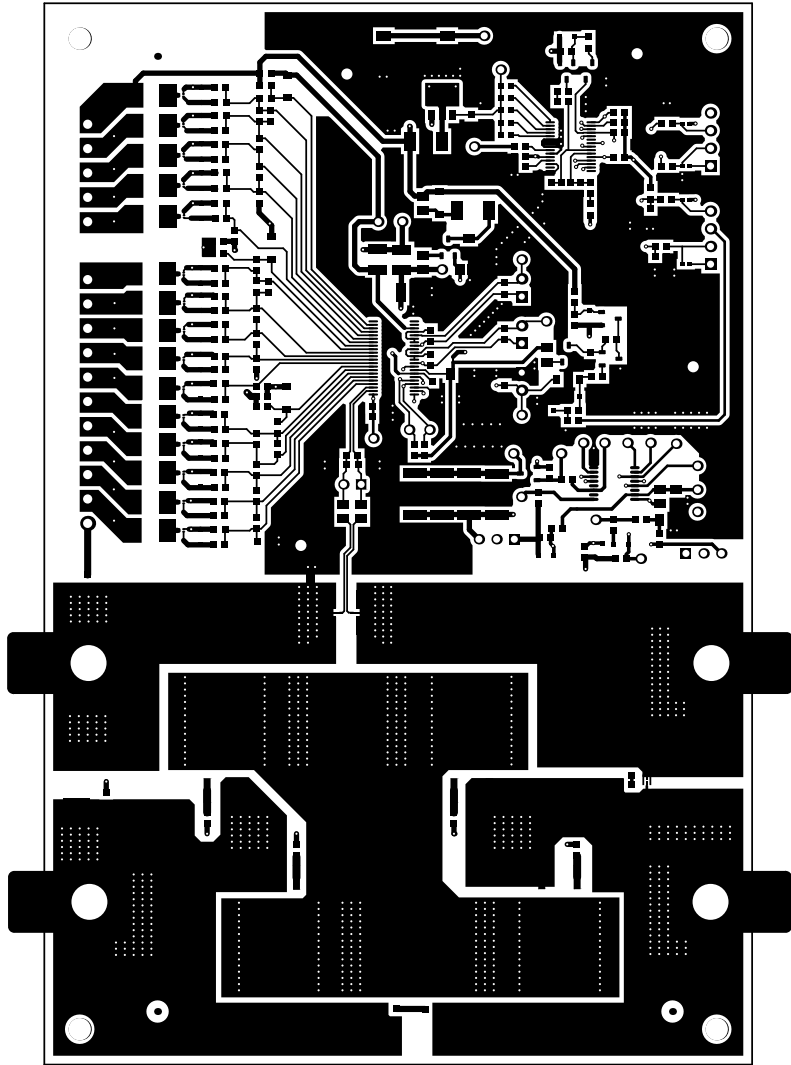


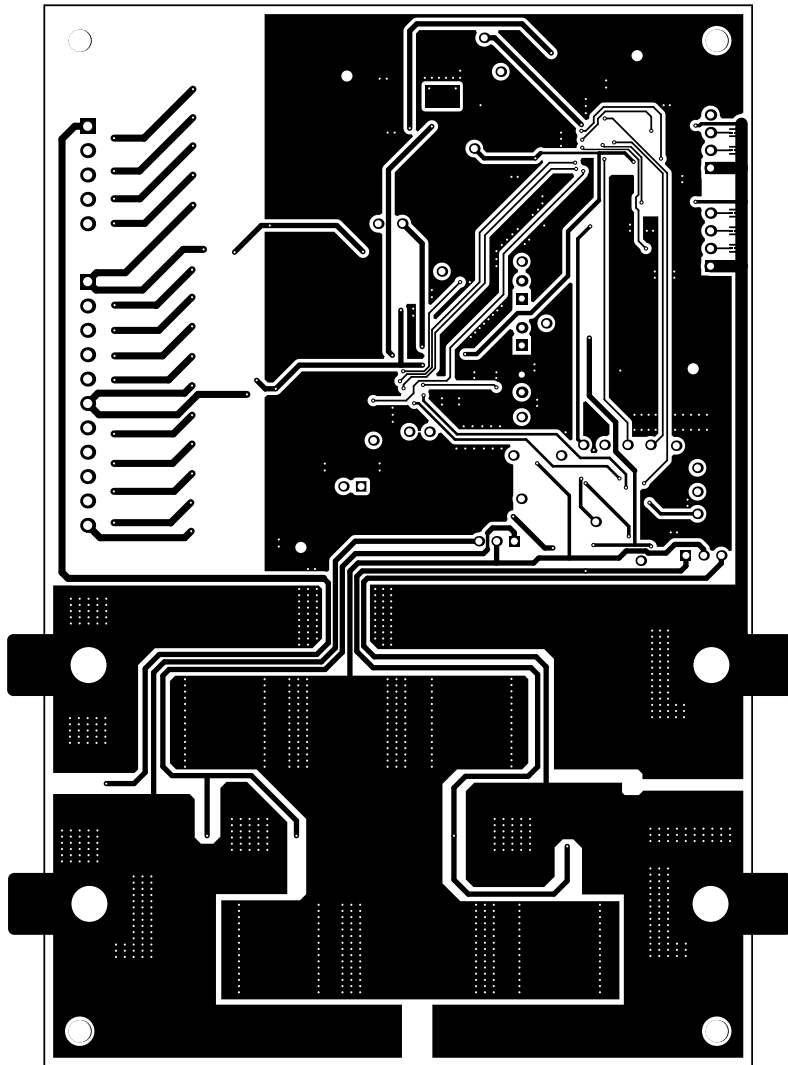
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00792		
PLOT NAME = Top Overlay	GENERATED : 3/15/2017 2:44:32 PM	TEXAS INSTRUMENTS	



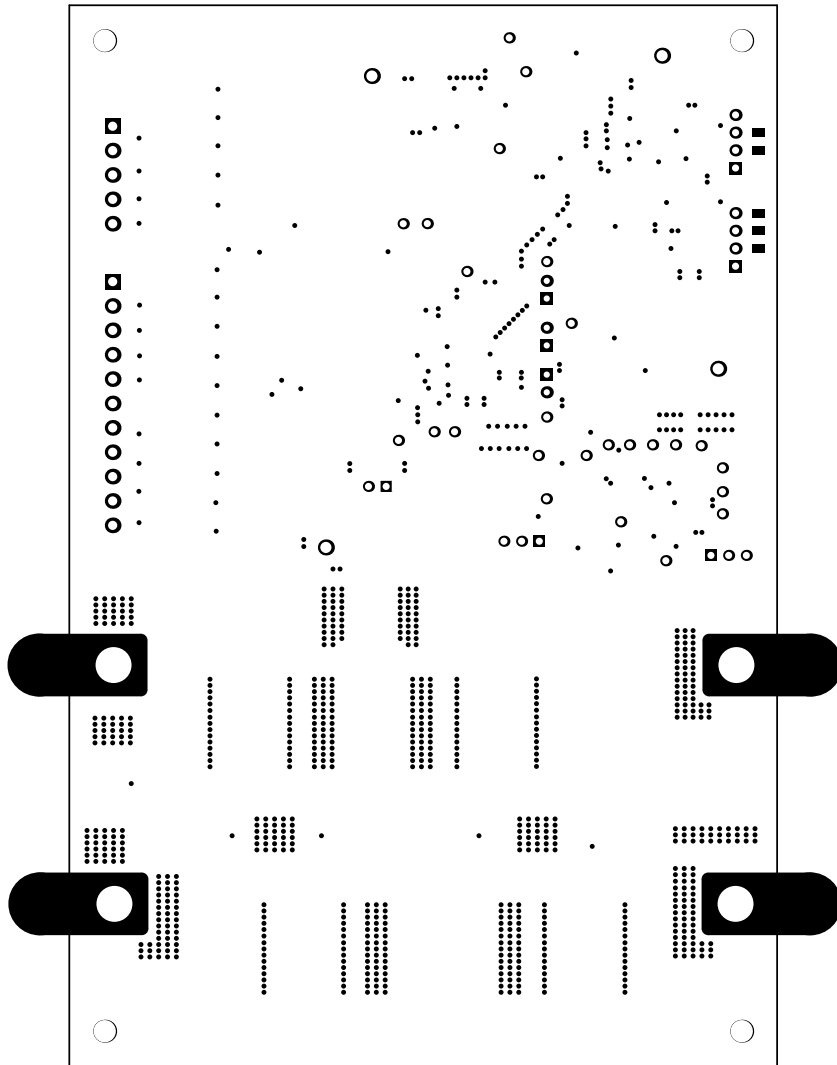
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00792		
PLOT NAME = Top Solder Mask	GENERATED : 3/15/2017 2:44:34 PM	TEXAS INSTRUMENTS	



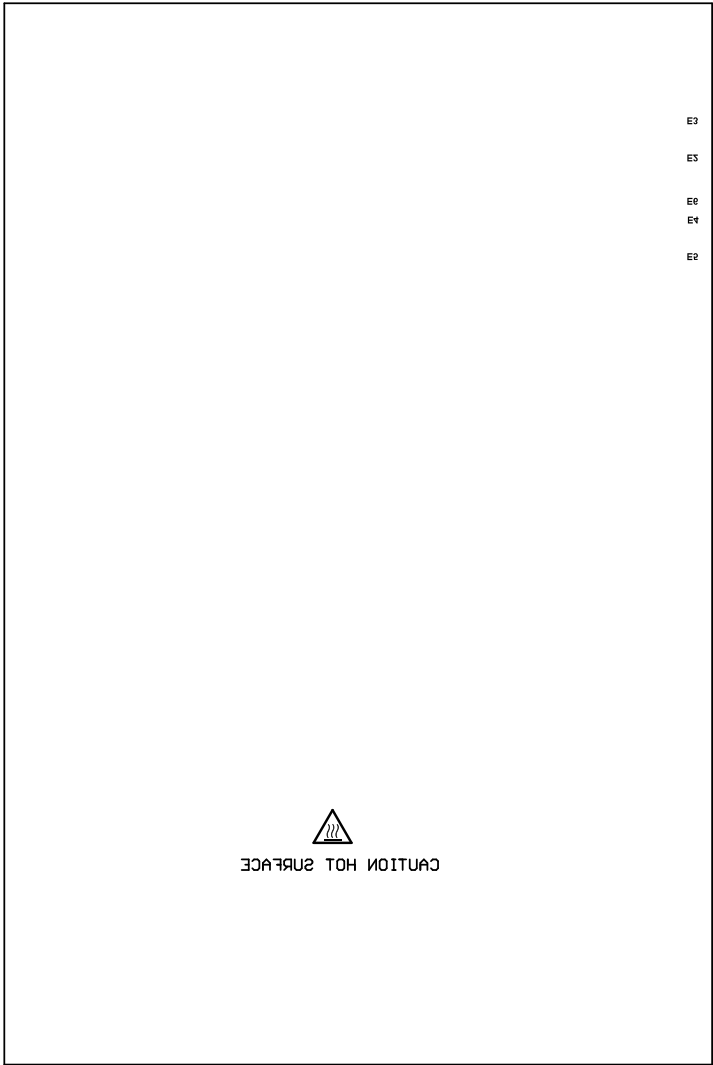
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00792		
PLOT NAME = Top Layer	GENERATED : 3/15/2017 2:44:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00792		
PLOT NAME = Bottom Layer	GENERATED : 3/15/2017 2:44:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00792		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/15/2017	2:44:37 PM	TEXAS INSTRUMENTS

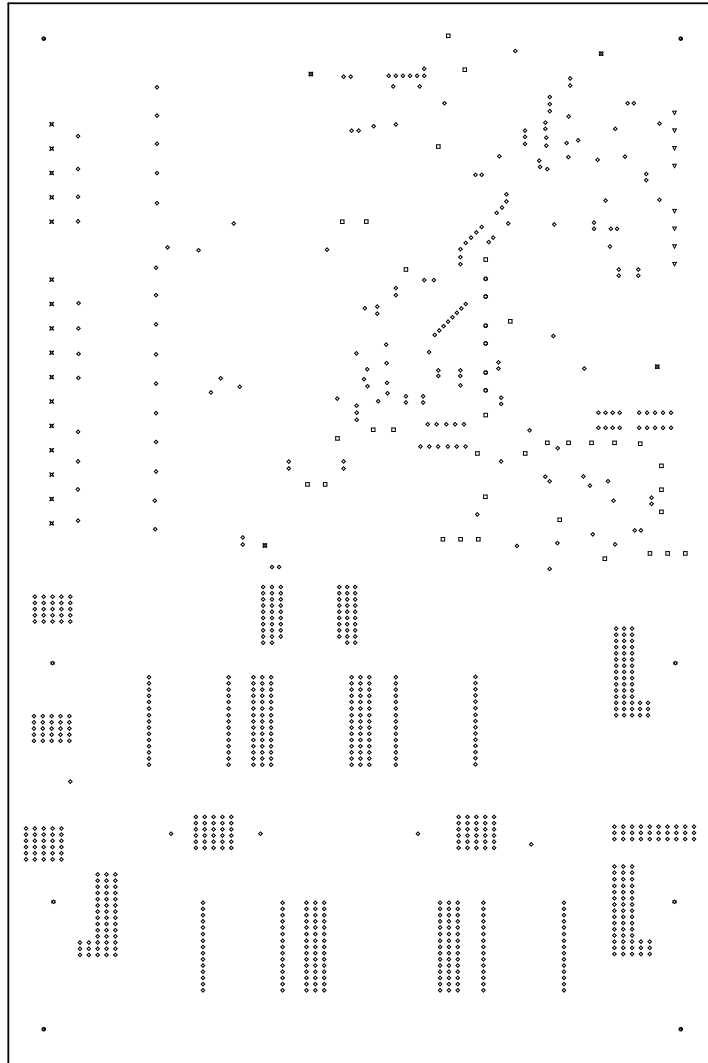


E3
E5
E6
E4
E2

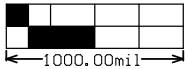
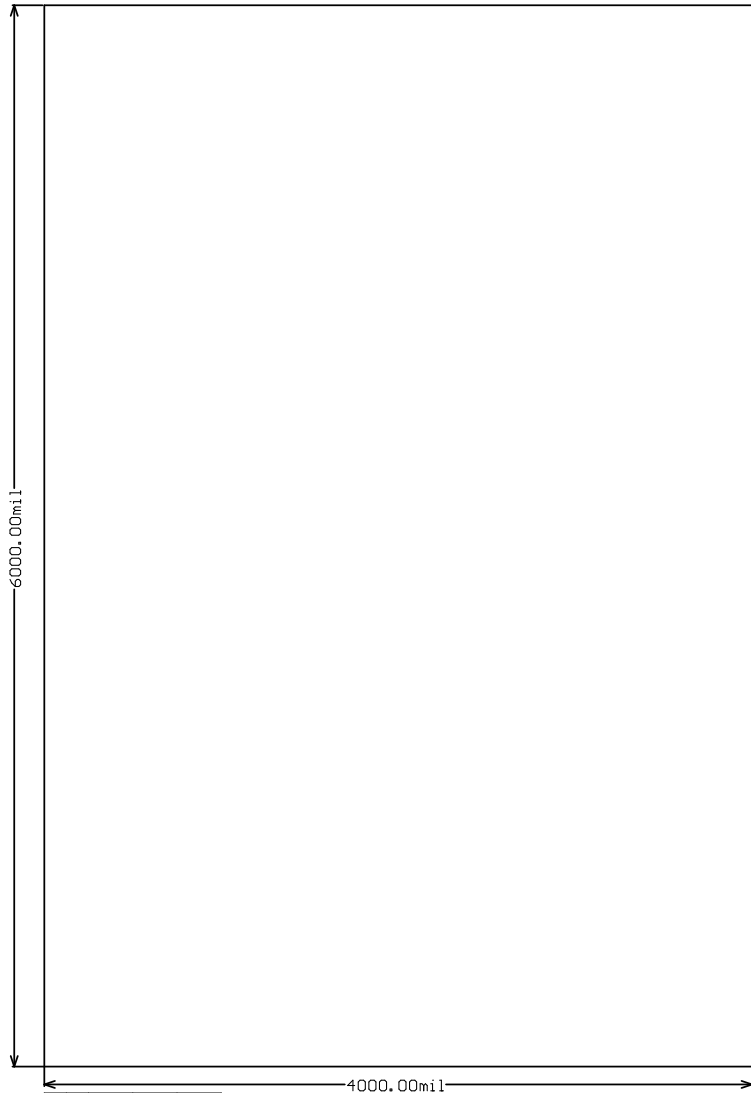

CAUTION HOT SURFACE

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00792		
PLOT NAME = Bottom Overlay	GENERATED : 3/15/2017 2:44:39 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
●	4	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	
◊	890	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	6	35.00mil (0.889mm)	PTH	Round	Top Layer - Bottom Layer	
□	33	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	8	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	16	52.00mil (1.321mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	4	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊚	4	203.15mil (5.160mm)	PTH	Round	Top Layer - Bottom Layer	
965 Total						



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00792		
PLOT NAME = Drill Drawing	GENERATED : 3/15/2017	2: 44: 40 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00792	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00792		
PLOT NAME = Board Dimensions	GENERATED : 3/15/2017 2:44:42 PM	TEXAS INSTRUMENTS	

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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